



X-1574 US  
10/796,471

PATENT  
Conf. No.: 2282

IN THE UNITED STATES PATENT OFFICE

Applicant: Leilei Zhang  
Assignee: Xilinx, Inc.  
Title: Metal Lid with Improved Adhesion to Package Substrate  
Serial No.: 10/796,471 Filing Date: March 9, 2004  
Examiner: Jose R. Diaz Art Unit: 2815  
Docket No.: X-1574 US Conf. No.: 2282

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT IN RESPONSE TO THE FINAL OFFICE ACTION

Dear Sir:

In response to the final Office action mailed from the Patent Office on October 16, 2006, please consider the following arguments and reconsider all pending claims. No amendments to the claims are made; therefore, this response does not include a listing of the claims.

**Amendments to the Specification** begin on page 2 of this paper.

**Listing of the Claims** there are no amendments to the claims but a listing of claims begins on page 4 of this paper.

**Amendments to the Drawings** begin on page 9 of this paper and include a replacement sheet.

**Remarks** begin on page 10 of this paper.

An **Appendix** including an amended drawing figures (Figures 2A-C) is attached following page 18.

**Exhibit A**, *Total Dispensing Solutions*, published by Asymtek (Spring 1998) is attached.

A **Statement of the Summary of the Interview** held on November 30, 2006 with Examiner Diaz is enclosed.

12/19/2006 BABRAHA1 00000003 240040 10796471

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02 FC:1201 200.00 DA